

MAZK068D

Silicon planer type

Constant voltage, constant current, waveform clipper and surge absorption circuit

■ Features

- Mini type package (5-pin)
- Four anode-common element wiring of MA3068

■ Absolute Maximum Ratings (Ta= 25°C)

Parameter	Symbol	Rating	Unit
Average forward current	$I_{F(AV)}$	100 * ¹	mA
Instantaneous forward current	I_{FRM}	200 * ¹	mA
Total power dissipation	P_{tot} * ²	100 * ¹	mW
Non-repetitive reverse surge power dissipation	P_{ZSM} * ³	15	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

*¹ Working value in a single piece

*² With a printed-circuit board

*³ t=100μs, T_j=150°C

■ Electrical Characteristics (Ta= 25°C) *¹

Parameter	Symbol	Condition	min	typ	max	Unit
Forward voltage	V_F	$I_F=10mA$		0.8	0.9	V
Zener voltage	V_Z * ²	$I_Z=5mA$	6.40	6.80	7.20	V
Operating resistance	R_{ZK}	$I_Z=0.5mA$			140	Ω
	R_Z	$I_Z=5mA$		6	15	Ω
Reverse current	I_{R1}	$V_R=4V$			2	μA
	I_{R2}	$V_R=5.9V$			60	μA
Temperature coefficient of zener voltage	S_Z * ³	$I_Z=5mA$	1.2	3.0	4.5	mV/°C
Terminal capacitance	C_t	$V_R=0V, f=1MHz$			110	pF

Note 1. Test method : Depend on JIS C7031 testing

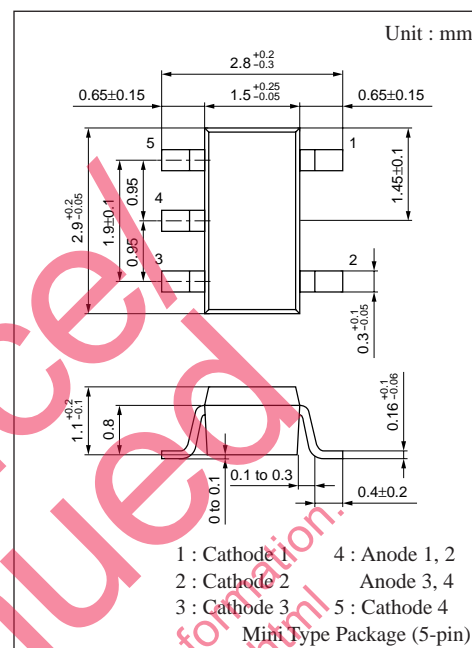
2. Rated input/output frequency : 5MHz

3. *¹ : The V_Z value is for the temperature of 25°C. In other cases, carry out the temperature compensation.

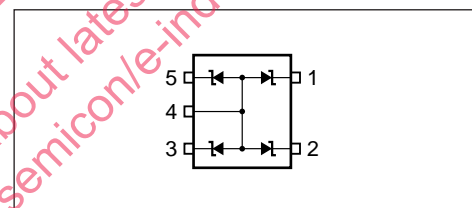
*² : Guaranteed at 20ms after power application

*³ : T_j= 25 to 150°C

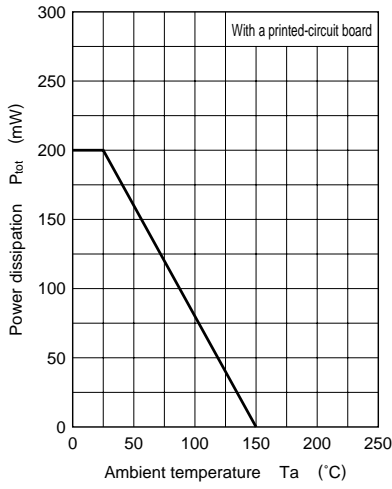
■ Marking



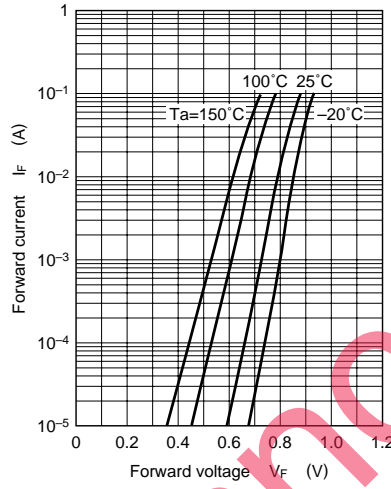
■ Internal Connection



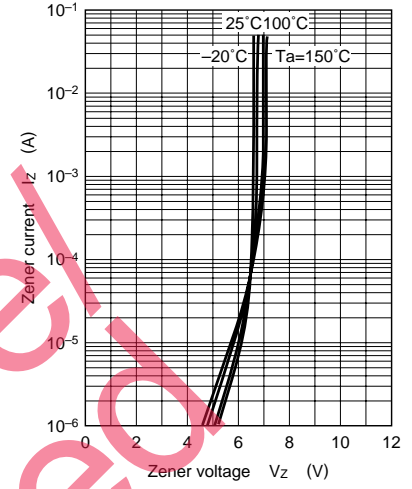
$P_{tot} - T_a$



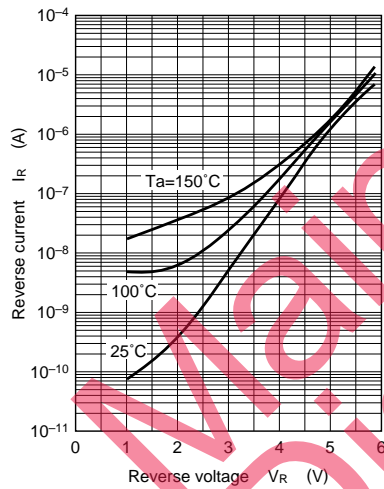
$I_F - V_F$



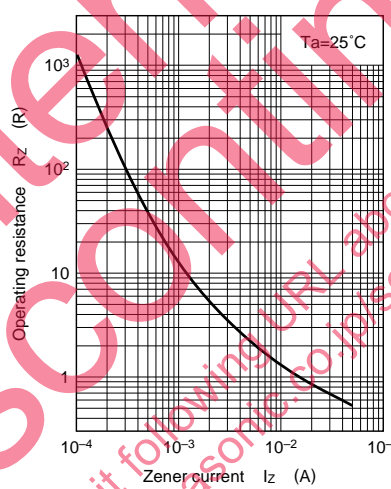
$I_Z - V_Z$



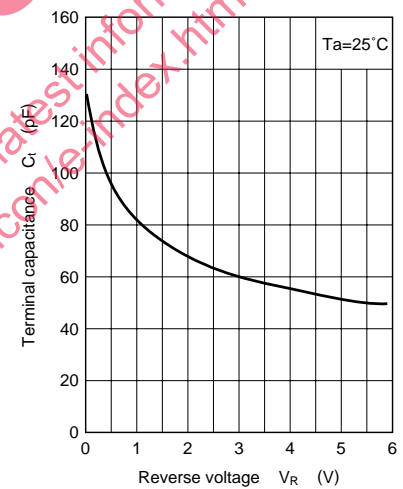
$I_R - V_R$



$R_Z - I_Z$



$C_t - V_R$



Discontinued
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